INFUNCTION TABLE

	Inp	Out	puts		
Preset	Clear	Clock	D	Q	Q
L	Н	×	×	Н	L
Н	L	×	×	L	Н
L	L	×	×	H*	H*
Н	Н	1	Н	Н	L
Н	Н	1	L	L	Н
Н	Н	L	×	Qo	$\overline{\mathbf{Q}}_0$

Notes) H; high level, L; low level, X; irrelevant

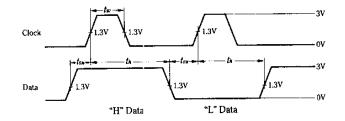
t; transition from low to high level

 Q_o ; level of Q before the indicated steady-state conditions were established.

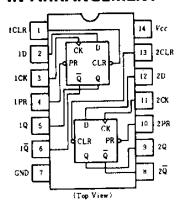
 \overline{Q}_o ; complement of Q_o or level of \overline{Q} before the indicated steady-state input conditions were established.

*: This configuration is nonstable, that is, it will not persist when preset and clear inputs return to their inactive (high) level.

TIMING DEFINITION



■PIN ARRANGEMENT



PRECOMMENDED OPERATING CONDITIONS

Item Clock frequency		Symbol	min	typ	max	Unit
		felock	0		25	MHz
Pulse	Clock High		25	_		ns
width	Clear Preset	tw	25	_	_	
Setup	"H"Data	tou	201	_	_	
time	"L"Data		20↑	_	-	ns
Hold ti	me	th	51	_	-	ns

Note) †; The arrow indicates the rising edge.

ELECTRICAL CHARACTERISTICS ($Ta = -20 \sim +75^{\circ}\text{C}$)

Item		Symbol	Test Conditions		min	typ*	max	Unit
		Vin			2.0	-	_	V
Input voltage		VIL			_	-	0.8	v
		Voн	$V_{CC} = 4.75 \text{ V}, V_{IH} = 2 \text{ V}, V_{IL} = 0.8 \text{ V}, I$	$oH = -400 \mu A$	2.7	-	-	V
Output voltage			$V_{CC} = 4.75 \text{V}, V_{IL} = 0.8 \text{V}, I_{OL} = 8 \text{mA}$	IoL = 8mA			0.5	v
		Vol	$V_{IH} = 2V$	$I_{OL} = 4 \mathrm{mA}$	_	_	0.4	
	D			· · · · · · · · · · · · · · · · · · ·	T -	_	20	
	Clear		12	0517 77 0 817			40	μA
	Preset	Itн	$V_{CC} = 5.25 \text{V}, V_I = 2.7 \text{V}$			_	40	
	Clock				-		20	
	D					_	-0.4	
	Clear		$V_{CC} = 5.25 \text{V}, V_t = 0.4 \text{V}$		_	<u> </u>	-0.8	mA
Input current	Preset	I_{LL}			_		-0.8	
	Clock						-0.4	
	D				_	_	0.1	
	Clear		II F 0517 I/ 937		_	_	0.2	mA
	Preset	Iı	$V_{CC}=5.25V, V_I=7V$	VI = IV			0.2	
	Clock					_	0.1	
Short-circuit output current		Ios	Vcc=5.25V		-20		-100	mΑ
Supply current		Icc**	Vcc=5.25V		T -	4	8	mΑ
Input clamp voltage		Vik	$V_{CC} = 4.75 \text{V}, I_{IN} = -18 \text{mA}$		T -		-1.5	V

* V_{CC}=5V, Ta=25°C

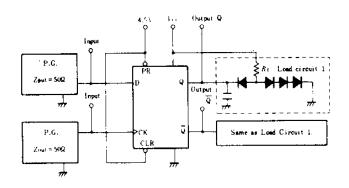
^{**} With all outputs open, I_{CC} is measured with the Q and $\overline{\mathbb{Q}}$ outputs high in turn. At the time of measurement, the clock input is grounded.

ESWITCHING CHARACTERISTICS ($V_{CC} = 5V$, $T_a = 25^{\circ}C$)

Item	Symbol	Inputs	Outputs	Test Condition	min	typ	max	Unit
Maximum clock frequency	fmax.				25	33		MHz
Propagation delay time	tp t.H	Clock, Clear	o. ō	$C_L = 15 \text{pF}, R_L = 2 \text{k}\Omega$		13	25	ns
	tphL	or Preset	Q, Q		_	25	40	ns

TESTING METHOD

- 1) Test Circuit
- 1.1) f_{max} , t_{PLH} , t_{PHL} (Clock $\rightarrow Q, \overline{Q}$)

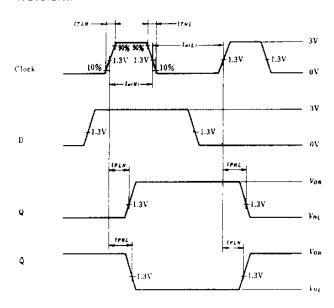


Notes) 1. Test is put into the each flip-flop

2. All diodes are 1S2074 (1).

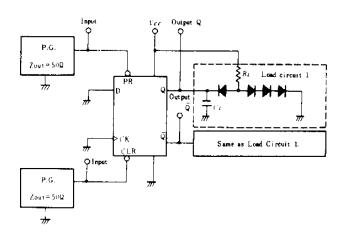
3. C_L includes probe and jig capacitance.

Waveform



Note) Clock input pulse; $t_{TLH} \le 15$ ns, $t_{THL} \le 6$ ns, PRR = 1MHz, duty cycle=50% and: for f_{max} , tTLH=tTHL ≤2.5ns.

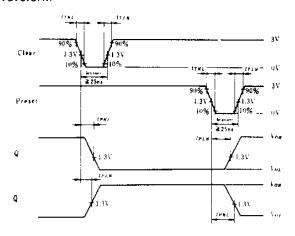
1.2) tpHL, tpLH (Clear or Preset→Q,Q)



Notes) 1. Test is put into the each flip-flop
2. All diodes are 1S2074 (1).

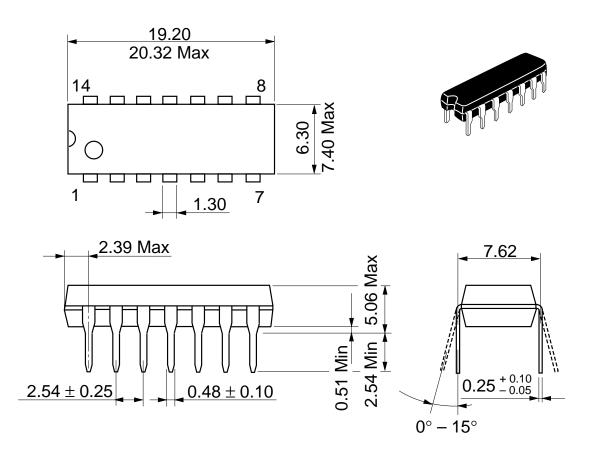
3. C_L includes probe and jig capacitance.

Waveform



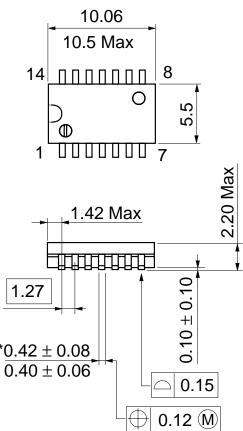
Note) Clear and preset input pulse; tTLH≤15ns, tTHL≤6ns, PRR=1MHz

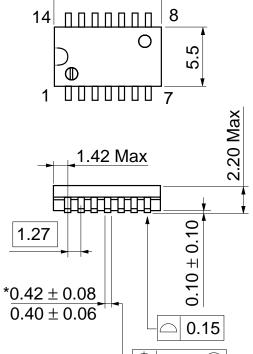
Unit: mm



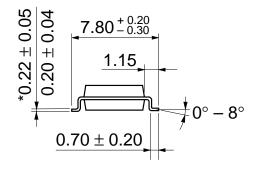
Hitachi Code	DP-14
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	0.97 g

Unit: mm





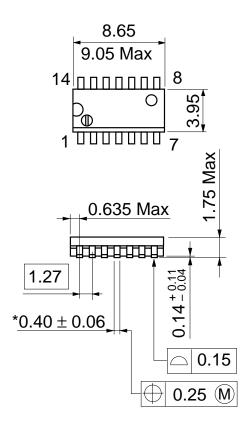




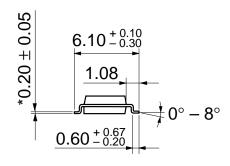
Hitachi Code	FP-14DA
JEDEC	
EIAJ	Conforms
Weight (reference value)	0.23 g

Dimension	including	the	plating	thickness
Bas	se materia	al dir	mensioi	1

Unit: mm







Hitachi Code	FP-14DN
JEDEC	Conforms
EIAJ	Conforms
Weight (reference	ce value) 0.13 g

*Pd plating

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